

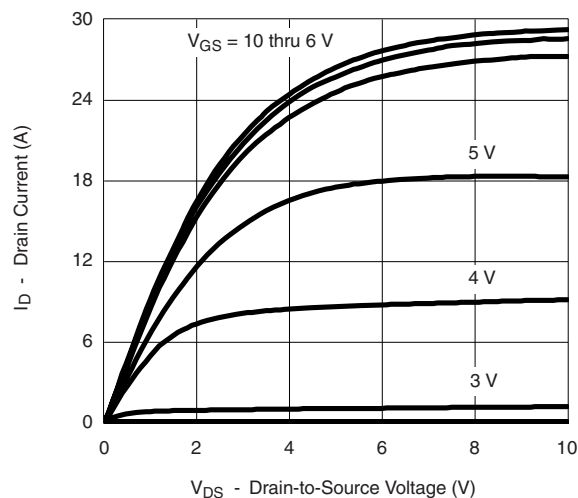
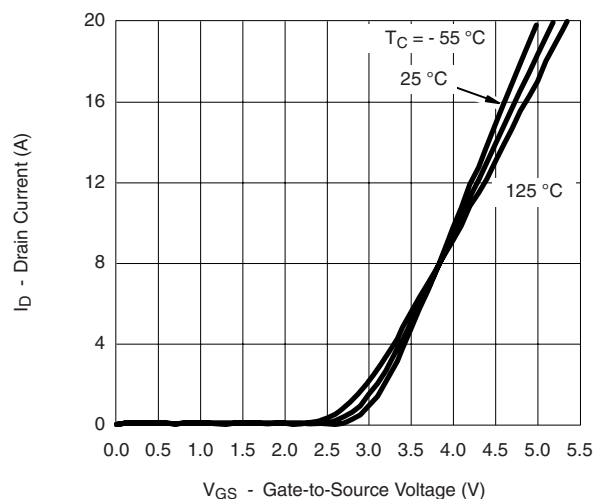
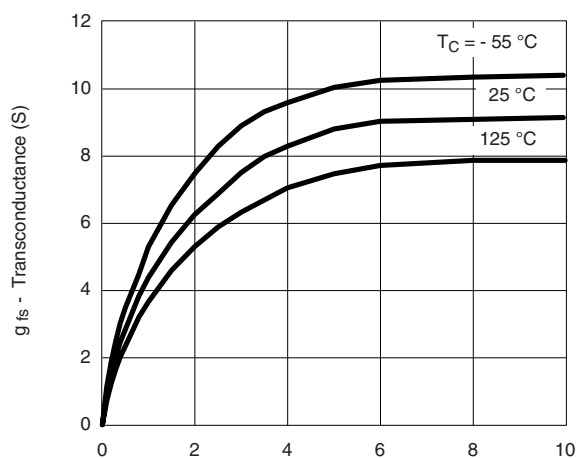
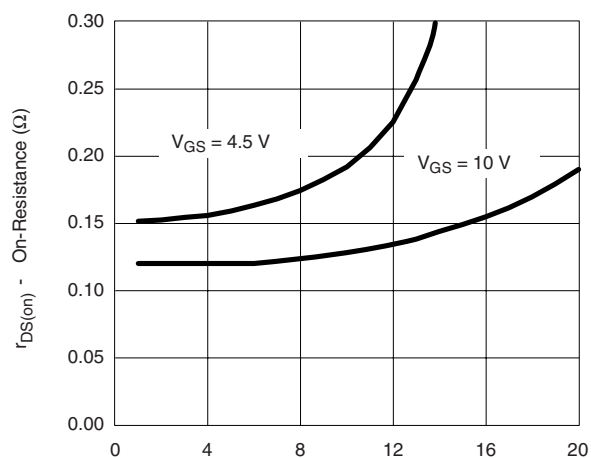
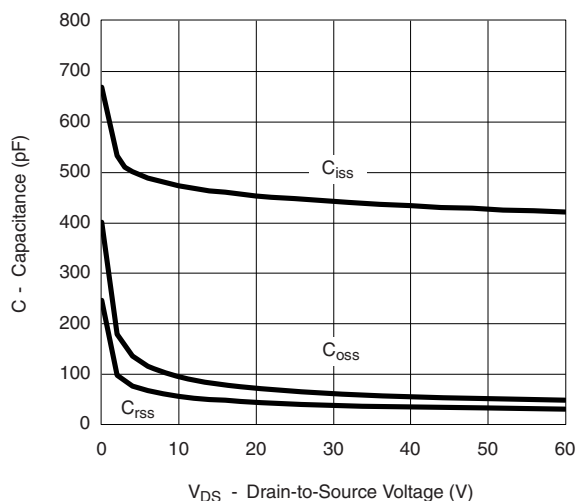
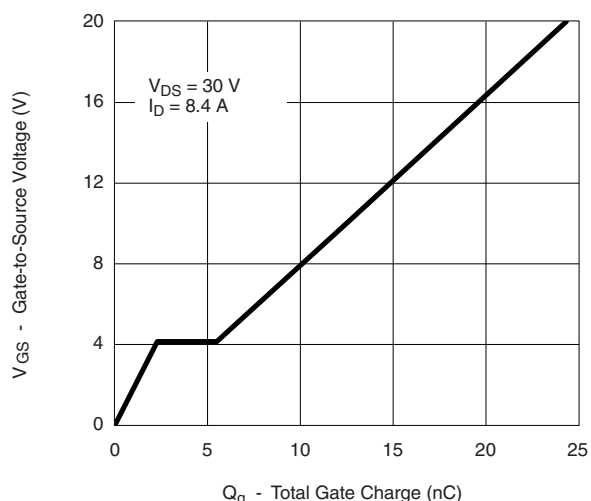


SPECIFICATIONS $T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{ V}$, $I_D = - 250\text{ }\mu\text{A}$	- 60			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = - 250\text{ }\mu\text{A}$	- 1.0	- 2.0	- 3.0	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = - 60\text{ V}$, $V_{GS} = 0\text{ V}$			- 1	μA
		$V_{DS} = - 60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 125\text{ }^{\circ}\text{C}$			- 50	
		$V_{DS} = - 60\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 175\text{ }^{\circ}\text{C}$			- 150	
On-State Drain Current ^b	$I_{D(on)}$	$V_{DS} = - 5\text{ V}$, $V_{GS} = - 10\text{ V}$	- 10			A
Drain-Source On-State Resistance ^b	$r_{DS(on)}$	$V_{GS} = - 10\text{ V}$, $I_D = - 5\text{ A}$		0.125	0.155	Ω
		$V_{GS} = - 10\text{ V}$, $I_D = - 5\text{ A}$, $T_J = 125\text{ }^{\circ}\text{C}$			0.280	
		$V_{GS} = - 10\text{ V}$, $I_D = - 5\text{ A}$, $T_J = 175\text{ }^{\circ}\text{C}$			0.350	
		$V_{GS} = - 4.5\text{ V}$, $I_D = - 2\text{ A}$		0.158	0.280	
Forward Transconductance ^b	g_{fs}	$V_{DS} = - 15\text{ V}$, $I_D = - 5\text{ A}$		8		S
Dynamic						
Input Capacitance	C_{iss}	$V_{DS} = - 25\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$		450		pF
Output Capacitance	C_{oss}			65		
Reverse Transfer Capacitance	C_{rss}			40		
Total Gate Charge	Q_g	$V_{DS} = - 30\text{ V}$, $V_{GS} = - 10\text{ V}$, $I_D = - 8.4\text{ A}$		12.5	19	nC
Gate-Source Charge	Q_{gs}			2.3		
Gate-Drain Charge	Q_{gd}			3.2		
Gate Resistance	R_g	$f = 1\text{ MHz}$		8.0		Ω
Turn-On Delay Time ^c	$t_{d(on)}$	$V_{DD} = - 30\text{ V}$, $R_L = 3.57\text{ }\Omega$ $I_D \cong - 8.4\text{ A}$, $V_{GEN} = - 10\text{ V}$, $R_G = 2.5\text{ }\Omega$		5	10	ns
Rise Time ^c	t_r			14	25	
Turn-Off Delay Time ^c	$t_{d(off)}$			15	25	
Fall Time ^c	t_f			7	12	
Source-Drain Diode Ratings and Characteristics ($T_C = 25\text{ }^{\circ}\text{C}$) ^b						
Pulsed Current	I_{SM}				- 20	A
Forward Voltage ^b	V_{SD}	$I_F = - 2\text{ A}$, $V_{GS} = 0\text{ V}$		- 0.9	- 1.3	V
Reverse Recovery Time	t_{rr}	$I_F = - 8\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$		50	80	ns
Reverse Recovery Time	Q_{rr}			80	120	nC

Notes:

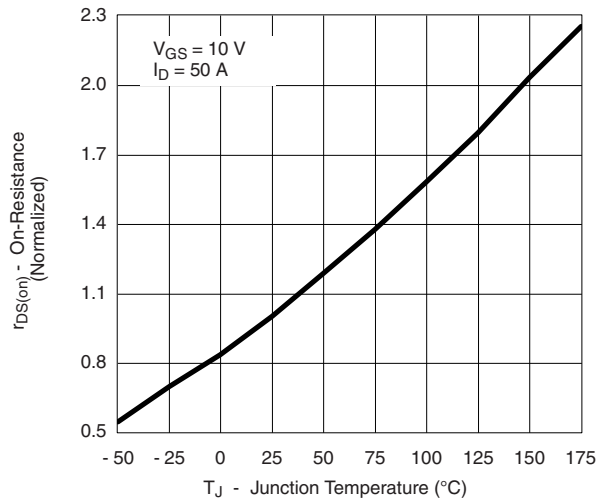
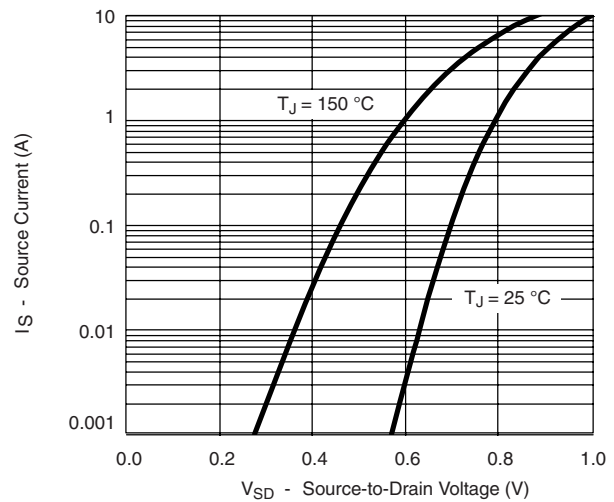
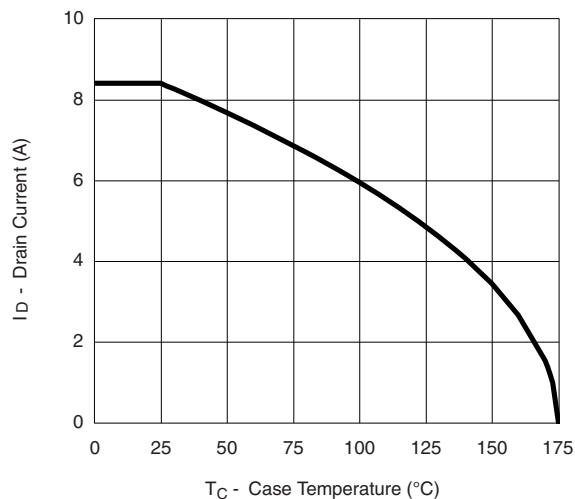
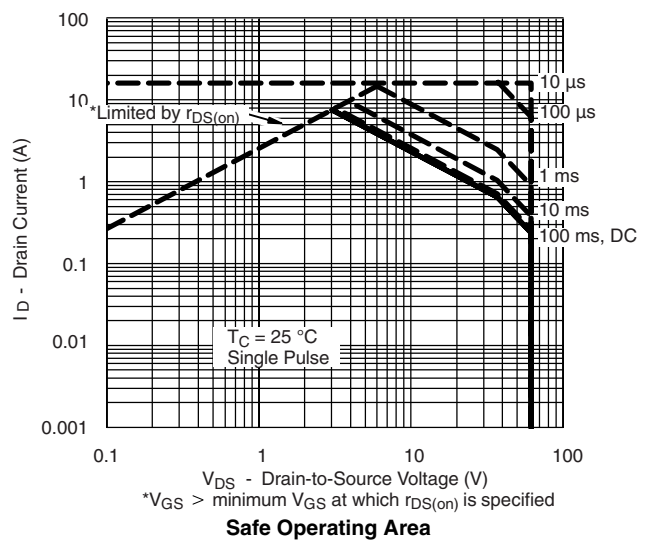
- a. Guaranteed by design, not subject to production testing.
 b. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
 c. Independent of operating temperature.

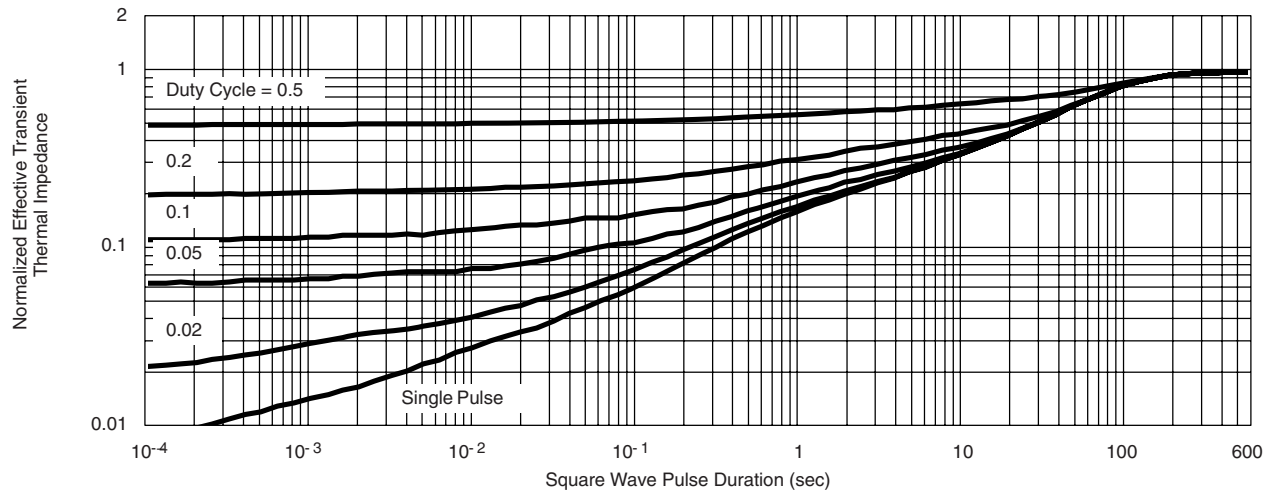
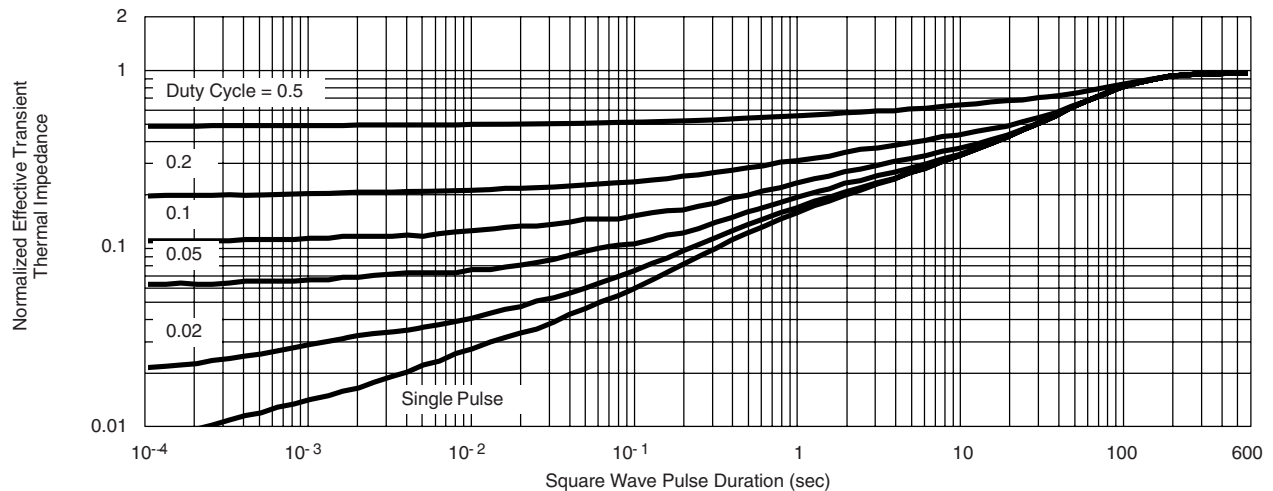
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** 25 °C unless noted**Output Characteristics****Transfer Characteristics****Transconductance****On-Resistance vs. Drain Current****Capacitance****Gate Charge**

SUD08P06-155L

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**TYPICAL CHARACTERISTICS** 25 °C unless noted**On-Resistance vs. Junction Temperature****Source-Drain Diode Forward Voltage****THERMAL RATINGS****Drain Current vs. Case Temperature****Safe Operating Area**

**THERMAL RATINGS****Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Case**

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